



Material Content Data Sheet



Sales Product Name		SPA15N60C3		Issued		29. August 2013		
MA#		MA001056032						
Package		PG-TO220-3-253		Weight*		2135.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.568	0.40	0.40	4012	4012
leadframe	non noble metal	iron	7439-89-6	1.431	0.07		670	
	inorganic material	phosphorus	7723-14-0	0.429	0.02		201	
	non noble metal	copper	7440-50-8	1428.770	66.91	67.00	669065	669936
wire	non noble metal	aluminium	7429-90-5	0.042	0.00	0.00	20	20
encapsulation	organic material	carbon black	1333-86-4	3.345	0.16		1566	
	plastics	epoxy resin	-	130.447	6.11		61086	
	inorganic material	silicondioxide	60676-86-0	535.169	25.06	31.33	250609	313261
leadfinish	non noble metal	tin	7440-31-5	21.462	1.00	1.00	10050	10050
plating	non noble metal	nickel	7440-02-0	1.764	0.08	0.08	826	826
solder	non noble metal	antimony	7440-36-0	0.405	0.02		189	
	noble metal	silver	7440-22-4	1.012	0.05		474	
	non noble metal	tin	7440-31-5	2.630	0.12	0.19	1232	1895
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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